
**PRODUCT/PROCESS
CHANGE NOTIFICATION**

PCN APMS/25/15692

Analog, Power, MEMS & Sensors (APMS)

**ST Manufacturing Reshaping (Analog_EWS ONLY AGR to TPY): Qualification
of Toa Payoh (Singapore) as new EWS Location.**

Issue date: 21st August 2026

Description of the change

Following Corporate PCI 15383 (Early Notification), about Company reshaping program, please be informed that EWS (Electrical Wafer Sorting) of Analog products listed here below will be transferred from ST Agrate (Italy) to ST Singapore.

Change Summary:

	Former	New
EWS/Location	ST Agrate	ST Singapore

Traceability:

Internal Traceability – Date code-

Step tracked in ST production systems and available real time on demand

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Affected products

Refer to below table for involved Commercial Products.

Specific devices not expressly listed in this table are included in this change.

CP code involved in qualification		
IPS4260LM	L5964Q-V0Y	MASTERGAN1
IPS4260LMTR	L5965SQ-V0T	MASTERGAN2
ISO808A	L5965SQ-VOY	MASTERGAN3
ISO808A-1	L5966R-V0T	MASTERGAN4
ISO808AQTR	L6362ATR	MASTERGAN5
ISO808AQTR-1	L6480H	PHOIB15DIE
ISO808ATR	L6480HTR	PHOIB15GELEP/RR
ISO808ATR-1	L6482H	PHOIB15GENDP/RR
ISO8200AQ	L6482HTR	PHX01
ISO8200AQTR	L9678P	POWERSTEP01
ISOSD61	L9678PTR	POWERSTEP01TR
ISOSD61L	L9678PTR-S	STDRIVEG600
ISOSD61LTR	L99VR033P	STDRIVEG600TR
ISOSD61TR	L99VR033PTR	STDRIVEG600W
KNX01	L99VR033QTR	STKNX
L5963DN-EHT	L99VR035P	STKNXTR
L5964BL-VYY	L99VR035PTR	UAW5CAP
L5964PQ-V0Y	L99VR035QTR	

Dual die (one of the dice qualified)

Qualification on going

Qualified

Reason

Die manufacturing: ST manufacturing reshaping program - Corporate PCI - Early Notification.

Date of implementation

First shipments forecast: one month after Qualification completion date (see below qualification results date for reference).

Impact of change

Form	Not Impacted
Fit	Not Impacted
Function	Not Impacted
Reliability	Not Impacted
Processability	Not Impacted

Qualification of the change (plan)

Qualification will be performed according to ST guidelines and ZVEI (ID SEM-TF01) for Automotive products.

Compliant with ST internal spec and ZVEI Guideline Product and Process Changes (PCN) 5.0 (Automotive products)				
		Line readiness	ED (Electrical Distribution, Cpk, analysis *)	Parametric analysis (Yield, Bin to Bin *)
Product		•	•	•

* Comparing wafers in old vs. new location

Disposition of former products

Delivery of current products will be done until stock depletion.

Qualification results

Qualification report including qualification results is enclosed at the end of this document:

Qualification completion date: Jan-2026.

Sampling plan

Customer samples are not planned; the switch of production will occur at product validation.

Qualification Report

Transfer of EWS (Electrical Wafer Sorting) from ST Agrate (Italy) to ST Singapore for Analog products

General Information	
Commercial Product	See above list
Product perimeter	Analog
Product group	APMS
Maturity level	Qualified

Locations	
Diffusion Plant	Multiple
Assembly Plant	Multiple
Reliability Lab	N/A

Assessment	
Pass	X
Fail	

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1. APPLICABLE AND REFERENCE DOCUMENTS

ZVEI	Change Standard Methodology
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2. GLOSSARY

EWS	Electrical Wafer Sorting
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3. RELIABILITY EVALUATION OVERVIEW

3.1. Objective

The objective of this report is to qualify the transfer of EWS (Electrical Wafer Sorting) from ST Agrate (Italy) to ST Singapore for products listed in PCN.

Qualification plan conducted following ZVEI matrix as follow:

	ZVEI DEFAULT	ZVEI WITH CONDITIONS	ST SELECTED	REASON FOR EXCEPTION OF TESTS
AEC-Q101 Revision E	•	•	X	
Parametric Verification	•	•	X	No characterization planned as only EWS is transferred*
Parameter-Analysis: Comparison of current with changed device characterization, electrical distribution	•	•	X	

*Characterization is meant for Final Test transfer, not applicable for this EWS transfer

3.2. Conclusion

Qualification Plan requirements have been fulfilled without exception. Line readiness tests, Electrical Distribution, Cpk, Yield and Bin to Bin analysis and comparison have all shown positive results. Based on these results, all devices are ready for the EWS transfer from ST Agrate to ST Singapore.

4. PRODUCT OR TEST VEHICLE CHARACTERISTICS

4.1. Device description

Refer to ST specification:

4.2. Construction note

	All parts listed in page 6
Wafer/Die fab. information	
Wafer fab manufacturing location	multiple
Technology	multiple
Wafer Testing (EWS) information	
Electrical testing manufacturing location	ST Singapore

5. TEST RESULTS SUMMARY

5.1. Lot information

Lot #	Part Number	Comment
Lot 1	STKNX	
Lot 2	POWERSTEP01	
Lot 3	L6362ATR	
Lot 4	IPS4260L	
Lot 5	PHX01	
Lot 6	L99VR035QTR	
Lot 7	FIBO2DASV01152	
Lot 8	IPS4260LM	
Lot 9	L99VR033P	
Lot 10	L99VR035P	
Lot 11	L99VR033QTR	
Lot 12	PHOIB15GELEP/RR	
Lot 13	PHOIB15DIE	
Lot 14	L5965SQ-V0T	
Lot 15	L5966R-V0T	
Lot 16	L5964L-TR	
Lot 17	L5963DN-EHT	
Lot 18	ISOSD61	
Lot 19	L9678P	

Detailed results in below chapter will refer to these references.

5.2. Test plan

Qualification of the change (plan)			
Qualification will be performed according to and ST guidelines and ZVEI (ID SEM-TF01) for Automotive products.			
Compliant with ST internal spec and ZVEI Guideline Product and Process Changes (PCN) 5.0 (Automotive products)			
	Line readiness	ED (Electrical Distribution, Cpk, analysis *)	Parametric analysis (Yield, Bin to Bin *)
Product	•	•	•

*comparing wafers in ol vs. new location

5.3. results summary

Item	Qualification activity	Sample size	STKNX	POWERSTEP01	L6362ATR	IPS4260L	PHX01	L99VR035QTR	FIBO2DASV01152	IPS4260LM
EWS line transfer	Line readiness	1 lot	PASS	PASS	PASS	PASS	PASS	PASS	PASS	PASS
	ED (Electrical Distribution, Cpk analysis)	1 full wafers	PASS	PASS	PASS	PASS	PASS	PASS	PASS	PASS
	Parametric analysis (Yield, Bin to Bin)	1 full wafers	PASS	PASS	PASS	PASS	PASS	PASS	PASS	PASS

Item	Qualification activity	Sample size	L99VR033P	L99VR035P	L99VR033QTR	PHOIB15GELEP/RR	PHOIB15DIE	L5965SQ-V0T	L5966R-V0T	L5964L-TR	L5963DN-EHT
EWS line transfer	Line readiness	1 lot	PASS	PASS	PASS	PASS	PASS	PASS	PASS	PASS	PASS
	ED (Electrical Distribution, Cpk analysis)	1 full wafers	PASS	PASS	PASS	PASS	PASS	PASS	PASS	PASS	PASS
	Parametric analysis (Yield, Bin to Bin)	1 full wafers	PASS	PASS	PASS	PASS	PASS	PASS	PASS	PASS	PASS

Item	Qualification activity	Sample size	ISOSD61	L9678P							
EWS line transfer	Line readiness	1 lot	PASS	PASS							
	ED (Electrical Distribution, Cpk analysis)	1 full wafers	PASS	PASS							
	Parametric analysis (Yield, Bin to Bin)	1 full wafers	PASS	PASS							

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